SCBS143P - MAY 1992 - REVISED SEPTEMBER 2003

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V **Operation and Low Static-Power** Dissipation
- **Support Mixed-Mode Signal Operation** (5-V Input and Output Voltages With 3.3-V V_{CC})
- **Support Unregulated Battery Operation** Down to 2.7 V
- Typical VOLP (Output Ground Bounce) $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V_{CC} and GND Pins Minimize **High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- Ioff and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

SN54LVTH16245A . . . WD PACKAGE SN74LVTH16245A . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)

	`	,	
1DIR	1	48	10E
1B1	2	47	1A1
1B2			1A2
GND [4		GND
_	l '		
1B3		44	1A3
1B4	6	43	
V _{CC}	7	42	
1B5 🛚	8		1A5
1B6 🛚	9		1A6
GND [10	39	GND
1B7 🛚	11	38	1A7
1B8 🛚	12	37	1A8
2B1	13	36	2A1
2B2	14	35	2A2
GND [15	34	GND
2B3 🛚	16	33	2A3
2B4 🛚	17	32	2A4
v _{cc} [18	31	V _{CC}
2B5 [19	30	2A5
2B6 🛚	20		2A6
GND [21	28	GND
2B7 🛚	22	27	2A7
2B8 🛚	23	26	2A8
2DIR	24	25	20E
		النيا	

description/ordering information

The 'LVTH16245A devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	CCOD DI	Tube	SN74LVTH16245ADL	LVTI IACOAFA
	SSOP – DL	Tape and reel	SN74LVTH16245ADLR	LVTH16245A
–40°C to 85°C	TSSOP - DGG	Tape and reel	SN74LVTH16245ADGGR	LVTH16245A
	TVSOP – DGV	Tape and reel	SN74LVTH16245ADGVR	LL245A
	VFBGA – GQL	Test and made	SN74LVTH16245AGQLR	110454
	VFBGA – ZQL (Pb-free)	Tape and reel	SN74LVTH16245AZQLR	LL245A
-55°C to 125°C	CFP – WD	Tube	SNJ54LVTH16245AWD	SNJ54LVTH16245AWD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





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description/ordering information (continued)

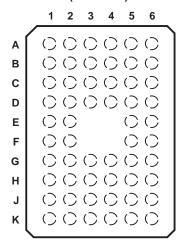
These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the devices so that the buses are effectively isolated.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

GQL OR ZQL PACKAGE (TOP VIEW)



terminal assignments

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	Vcc	Vcc	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	Vcc	Vcc	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 <mark>OE</mark>

NC - No internal connection

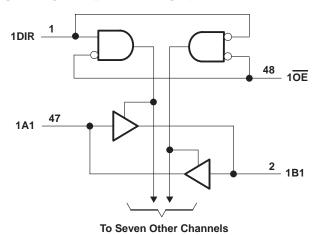
FUNCTION TABLE (each 8-bit section)

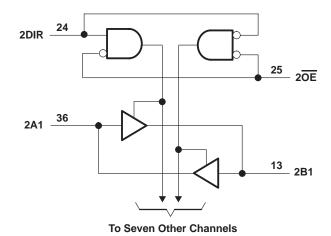
INP	UTS	ODED ATION				
OE	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	Χ	Isolation				



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logic diagram (positive logic)





Pin numbers shown are for the DGG, DGV, DL, and WD packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	-0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)0.5 V	
Current into any output in the low state, IO: SN54LVTH16245A	96 mA
SN74LVTH16245A	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVTH16245A	48 mA
SN74LVTH16245A	64 mA
Input clamp current, $I_{ K }(V_1 < 0)$	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
GQL/ZQL package	42°C/W
Storage temperature range, T _{stq} –	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS143P - MAY 1992 - REVISED SEPTEMBER 2003

recommended operating conditions (see Note 4)

			SN54LVTH	16245A	SN74LVTH	16245A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2		2		V
V _{IL}	Low-level input voltage		0.8		8.0	V	
VI	Input voltage			5.5		5.5	V
loн	High-level output current			-24		-32	mA
lOL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEST CONDITIONS		SN54L	VTH1624	15A	SN74LVTH16245A			UNIT		
PAR	AMETER	TEST COI	NUTTIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII		
VIK		$V_{CC} = 2.7 \text{ V}, \qquad I_{I} = -18 \text{ mA}$				-1.2			-1.2	V		
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0.2			V _{CC} -0.2					
.,		$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$	2.4			2.4			V		
VOH		V 2 V	$I_{OH} = -24 \text{ mA}$	2						V		
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2					
		V 27V	I _{OL} = 100 μA			0.2			0.2			
		V _{CC} = 2.7 V	I _{OL} = 24 mA			0.5			0.5			
\/ - ·			I _{OL} = 16 mA			0.4			0.4	V		
V_{OL}		\\ 0\\	I _{OL} = 32 mA			0.5			0.5	V		
		V _{CC} = 3 V	$I_{OL} = 48 \text{ mA}$			0.55						
			$I_{OL} = 64 \text{ mA}$						0.55			
	Control	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1			
	inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10			
I _I			V _I = 5.5 V			20			20	μА		
	A or B ports‡	V _{CC} = 3.6 V	VI = VCC			5			1			
	ports+		V _I = 0			-5			-5			
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ		
		V 2V	V _I = 0.8 V	75			75					
I(hold)	A or B ports	V _{CC} = 3 V	V _I = 2 V	-75			-75			μΑ		
·I(IIOIG)	Troi B pond	V _{CC} = 3.6 √§,	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						500 -750	μ		
lozpu		$\frac{\text{VCC}}{\text{OE}} = 0 \text{ to } 1.5 \text{ V, V}_{\text{O}} = 0$	0.5 V to 3 V,			±100*			±100	μΑ		
lozpd		$\frac{\text{VCC}}{\text{OE}}$ = 1.5 V to 0, V _O = 0.5 V to 3 V, $\frac{\text{OE}}{\text{OE}}$ = don't care				±100*			±100	μΑ		
		V _{CC} = 3.6 V,	Outputs high			0.19			0.19			
ICC	lcc	$I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low			5			5	mA		
			Outputs disabled			0.19			0.19	1		
ΔICC¶		$V_{CC} = 3 \text{ V to } 3.6$, One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at V_{CC} or GND			_	0.2		_	0.2	mA		
Ci		V _I = 3 V or 0			4			4		pF		
Cio		V _O = 3 V or 0			10			10		pF		

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] Unused pins at V_{CC} or GND. § This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS143P - MAY 1992 - REVISED SEPTEMBER 2003

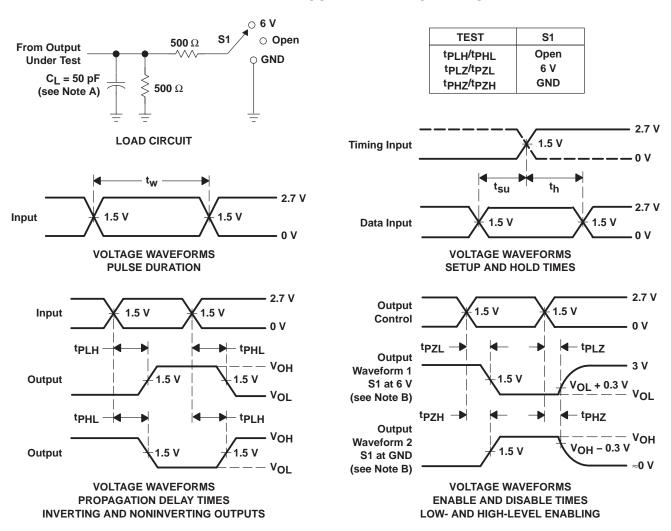
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

			s	SN54LVTH16245A			SN74LVTH16245A					
PARAMETER	FROM (INPUT)			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX	
tPLH	A == D	D. o.s. A	0.5	4.5		4.6	1.5	2.3	3.3		3.7	
t _{PHL}	A or B	B or A	0.5	4.4		3.9	1.3	2.1	3.3		3.5	ns
^t PZH	<u>M</u>	A D	0.5	6.5		6.6	1.5	2.8	4.5		5.3	
tPZL	OE	A or B	0.5	5.4		6.2	1.6	2.9	4.6		5.2	ns
^t PHZ	<u>M</u>	A or D	1	6.8		7	2.3	3.7	5.1		5.5	20
tPLZ	OE	A or B		6.2		6.3	2.2	3.5	5.1		5.4	ns
tsk(o)									0.5		0.5	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{Q} = 50~\Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

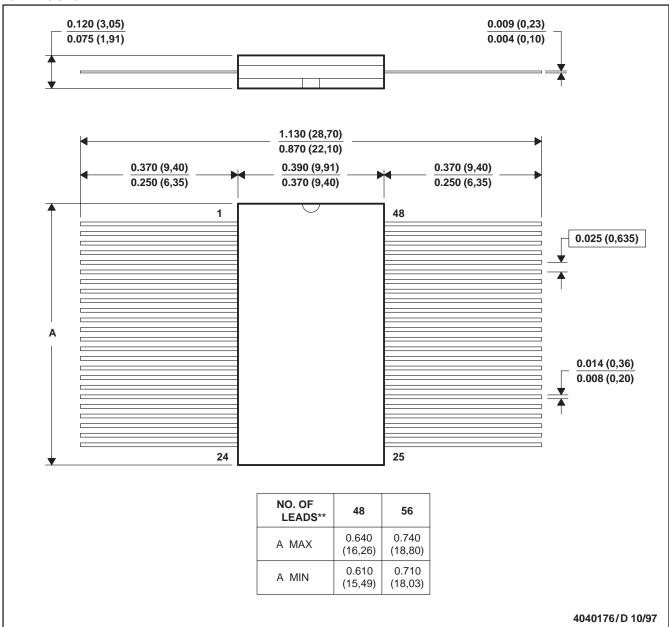
Figure 1. Load Circuit and Voltage Waveforms



WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

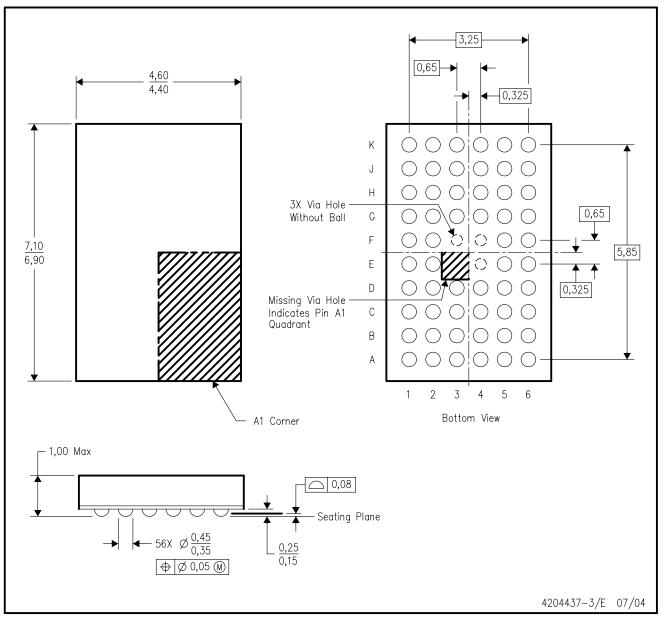
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB



ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



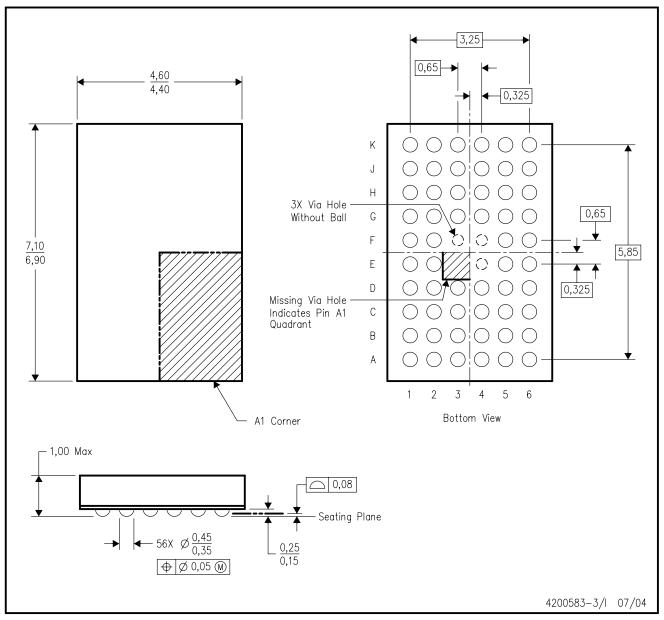
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153 14/16/20/56 Pins – MO-194



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

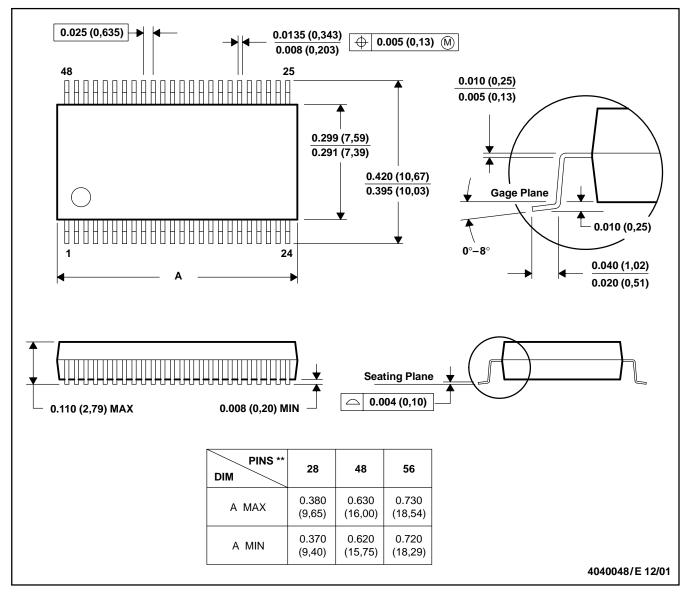
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

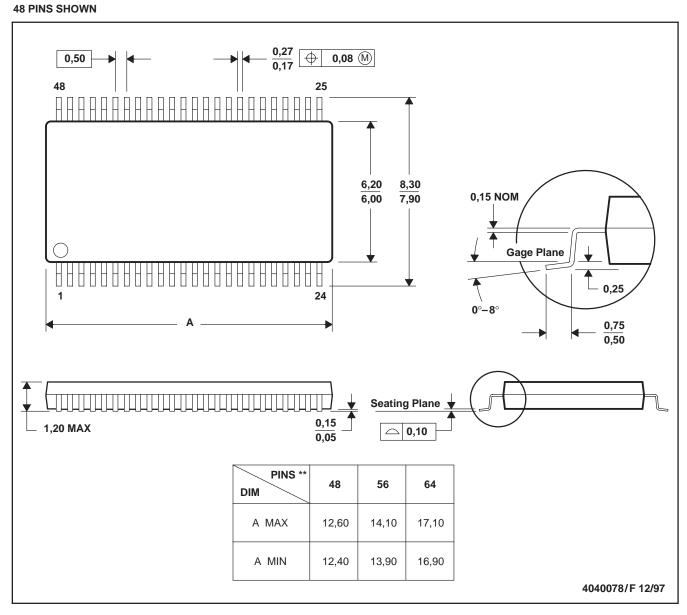
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118



DGG (R-PDSO-G**)

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PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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